

GRF1-J-P-04-E-ST-TH1

GRF1-J-P-04-E-ST-TH1-E

(5.00 mm) .197"

GRF1-J, GRF1-P SERIES

50 Ω GANGED MICRO-MINI RF SYSTEMS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?GRF1-J or www.samtec.com?GRF1-P

Shell Material:

Brass

Insulator Material:

PTFE

Contact Material:

BeCu

Pin Material:

Brass

Plating:

30 μ" (0.76 μm) Au
over 50 μ" (1.27 μm) Ni

Current Rating (GRF1-J/GRF1-P):

Signals: 3.6 A per pin
(8 adjacent pins powered)

Grounds: 6.2 A per pin
(8 adjacent pins powered)

Operating Temp Range:

-40 °C to +90 °C

Impedance:

50 Ω

Dielectric

Withstanding Voltage:

500 Vrms, 50 Hz

Dielectric Working Voltage:

170 Vrms, 50 Hz

Frequency Range:

0-6 GHz

RoHS Compliant:

Yes

GRF1

J

P

NO. OF JACKS

PLATING

LEAD STYLE

TH1

INSERT OPTION

Mates with:

GRF1-P, GRF1-C,
GRF1H-C-02, -04,
-06, -08

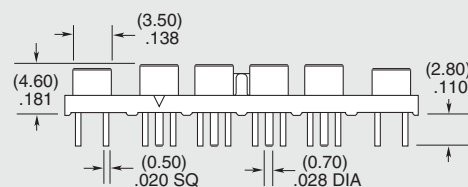
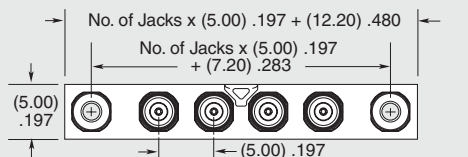
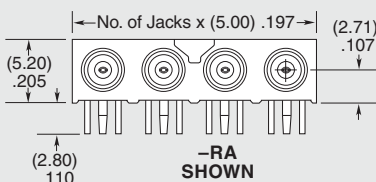
-E

= 30 μ" (0.76 μm)
Gold on Center
Conductor & Tail,
Gold Flash on
Shell and Tails

-ST
= Vertical-RA
= Right-
angle

-E

= #1 - 64 Through-hole
Threaded Insert,
Mates with GRF1-C with
captive screw option

-ST-TH1-E
SHOWN

PROCESSING

Lead-Free Solderable:

Yes

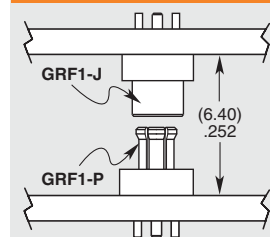
RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality



FILE NO. E111594

APPLICATION



OTHER SOLUTIONS

- Cable assembly
(see GRF1-C Series)

GRF1

P

P

NO. OF PLUGS

PLATING

ST

TH1

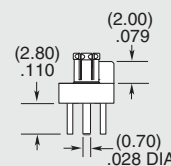
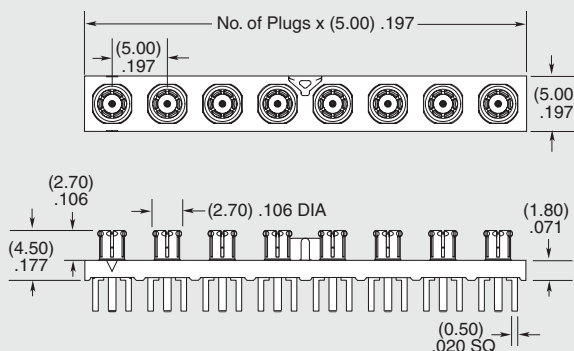
Mates with:

GRF1-J

-02, -04, -06, -08

-E

= 30 μ" (0.76 μm) Gold on Center Conductor & Tail,
Gold Flash on Shell and Tails



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Components must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.